

b350

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微信改绑手机号-小茴香的功效



2023年3月20日发(作者：跳棋棋盘的画法)

243D-0009C-01P1/11

.,LTD

ReferenceOnly

ChipCommonModeChokeCoil

DLM0NS□□□□HY2□ReferenceSpecification

ThisreferencespecificationappliestoChipCommonModeChokeCoilDLM0NSSeriesfordifferentialsignal
interfaceinElectronics.

mbering

(ex.)DLM0NSB120HY2D

(1)(2)(3)(4)(5)(6)(7)(8)(9)(10)

(1)ChipCommonModeChokeCoil

(2)Structure(M:MonolithicType)

(3)Dimension(LW)

(4)TypeS:Magneticallyshieldedonecircuittype

(5)Category

Customer

PartNumber

Murata

PartNumber

CommonModeImpedance

(at100MHz,Under

StandardTestingCondition)

Rated

Voltage

Withstanding

Voltage

Rated

Current

DC

Resistance

Insulation

Resistance

Cut-off

Frequency

DLM0NSB120HY2D

125

5V(DC)12.5V(DC)

160mA

1.225%

10M

min.

8GHz(Typ.)

DLM0NSB120HY2B

DLM0NSB280HY2D

2830%130mA

1.925%

DLM0NSB280HY2B

DLM0NSN500HY2D

5025%

5V(DC)12.5V(DC)100mA

2.725%

10M

min.

5GHz(Typ.)

DLM0NSN500HY2B

DLM0NSN900HY2D

9025%4.025%

2GHz(Typ.)

DLM0NSN900HY2B

OperatingTemperature:-40to+85CStorageTemperature:-40to+85C

rdTestingConditions

Temperature:OrdinaryTemperature15to35CTemperature:202C

Humidity:OrdinaryHumidity25to85%(RH)Humidity:60to70%(RH)

AtmosphericPressure:86to106kPa

ndDimensions

■ EquivalentCircuits

Nopolarity

(6)Impedance(100MHz)

(7)CircuitH:CharacteristicImpedance100system

(8)Features

(9)NumberofLine

(10)PackagingCodeD:Taping/B:Bulk

(1)(2)

(4)(3)

Nopolarity

■ UnitMass(Typicalvalue)

0.9mg

243D-0009C-01P2/11

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g

NoMarking.

icalPerformance

ecificationTestMethod

7.1CommonMode

Impedance

ingFrequency:1001MHz(10.)

MeasuringEquipment:KEYSIGHT4291Aorthe

equivalents

(我学会了什么作文400字 Incaofdoubtinstandardcondition,theheat

treatment(200C,about10min)shallbeapplied.

7.2Withstanding

Voltage

Itage:2.5timesforRatedVoltage

Time:1to5s

ChargeCurrent:1mAmax.(10.)

7.3DCResistance

(Rdc)

ingcurrent:100mAmax.(10.)

7.4Insulation

Resistance(I.R.)

Measuringvoltage:RatedVoltage

Measuringtime:1minmax.(10.)

icalPerformance

ecificationTestMethod

8.1Appearanceand

Dimensions

InspectionandmeasuredwithSlideCalipers.

8.2SolderabilityTheelectrodesshallbeatleast

95%coveredwithnewsolder

coating.

Flux:Ethanol solution of rosin, 25(wt)%

Pre-Heating:150 $\pm$ 10 $^{\circ}$ C, 60 ~ 90s

Solder:Sn-3.0Ag-0.5Cu

Solder Temperature:230 $\pm$ 3 $^{\circ}$ C

Immersion Time:30.5s

Immersion and demersion rates:25mm/s

8.3 Resistance to

Soldering Heat

Meet Table 1.

Table 1

Flux:Ethanol solution of rosin, 25(wt)%

Pre-Heating:150 $\pm$ 10 $^{\circ}$ C, 60 ~ 90s

Solder:Sn-3.0Ag-0.5Cu

SolderTemperature:2705C

ImmersionTime:51s

Immersionandemersionrates:25mm/s

Thenmeasuredarterexposureintheroomcondition

for4hto48h.

8.4DropItshallbedroppedonconcreteorsteelboard.

Method:freefall

Height:1m

TheNumberofTimes:10times

8.5VibrationItshallbesolderedonthesubstrate.

OscillationFrequency:10to2000for20min

Totalamplitude:3.0mmorAccelerationamplitude

196m/s²whicheverissmaller.

TestingTime:Aperiodof4hoursineachof3

mutuallyperpendiculardirections.

8.6Bending

Strength

MeetTable2.

Table2

Substrate:(t=1.0mm).

Deflection:2mm

SpeedofApplyingForce:1.0mm/s

Keepingtime:60s

AppearanceNodamaged

CommonMode

Impedance

Change

within30%

I.R.

10Mmin.

DCResistance

Change

within30%

45

R230F

Deflection

45

Product

Pressurejig

AppearanceNodamaged

DCResistance

Change

within30%

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nmentalPerformance(Productsshallbesolderedontheglass-epoxysubstrate)

ecificationTestMethod

9.1Temperature

Cycle

MeetTable1.1Cycle

Step1-40C(+0C,-3C)/30(+3,-0)min

Step2OrdinaryTemp./within3min

Step3+85(+2C,-0C)/30(+3,-0)min

Step4OrdinaryTemp./within3min

Totalof100cycles.

Thenmeasuredafterexposureintheroomcondition

for4hto48h.

9.2HumidityTemperature:402C

Humidity:90to95%(RH)

Time:1000h(+48h,-0h)

Thenmeasuredafterexposureintheroomcondition

for4hto48h.

9.3HeatlifeTemperature:852C

TestVoltage:2timesforRatedVoltage

Time:1000h(+48h,-0h)

Thenmeasuredafterexposureintheroomcondition

for4hto48h.(10.)

9.4ColdResistanceTemperature:-402C

Time:1000h(+48h,-0h)

Thenmeasuredafterexposureintheroomcondition

for4hto48h.

altobeTested.

Whenmeasuringandsupplyingthevoltage,thefollowingterminalisapplied.

rminaltobeTested

10.1CommonMode

Impedance

10.2WithstandingVoltage

InsulationResistance

HeatLife

10.3DCResistance

ingmethodforcommonmodeimpedance.

Measuredcommonmodeimpedancemaybeincludedmeasurementerrorduetostraycapacitance,residual
inductanceoftestfixture.

Tocorrectthirror,thecommonmodeimpedanceshouldbecalculateasfollows;

(1)Measureadmittanceofthefixture(opened),GoBo.

(2)Measureimpedanceofthefixture(shorted),RsXs.

(3)Measureadmittanceofthespecimen,GmBm.

(4)Calculatecorrectedimpedance Z usingtheformulabelow.

$$Z = (R_x^2 + X_x^2)^{1/2}$$

Where

$R_x =$

$G_m - G_o$

$(G_m - G_o)^2 + (B_m - B_o)^2$

- R_s

$X_x =$

$-(B_m - B_o)$

$(G_m - G_o)^2 + (B_m - B_o)^2$

- X_s

12.P.C.B.,Flux,SolderandSolderingcondition

TestshallbedoneusingP.C.B.,Flux,SolderandSolderingconditionwhicharespecifiedinitem16exceptthe

caofbeingspecifiedspecialcondition.

I N

O U T

I N

O U T

I N

O U T

I N

O U T

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nceFrequencyCharacteristics(Typical)

DLM0NSN500HY2

DLM0NSN900HY2

DLM0NSB120HY2

DLM0NSB280HY2

Frequency(MHz)

Frequency(MHz)

DifferentialMode

CommonMode

DifferentialMode

CommonMode

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icationofPackagingFrequency

14.1AppearanceandDimensions(8mm-wide,2mmpitchPapertape)

14.2SpecificationofTaping

(1)Packingquantity(Standardquantity)10,000pcs./reel

(2)PackingMethod

ProductsshallbepackedinthecavityofthebatapeandaledbyCovertape.

(3)SprocketHole

Thesprocketholesaretotherightasthetapeispulledtowardtheur.

(4)Splicedpoint

Thecovertapehavenosplicedpoint.

(5)Missingcomponentsnumber

Missingcomponentsnumberwithin0.1%ofthenumberperreelor1pc.,whicheverisgreater,andarenot

cifiedquantityperreeliskept.

14.3 Pull Strength of Paper Tape

Paper Tape 5Nmin.

Cover Tape 10Nmin.

14.4 Peeling off force of Cover Tape

0.1 to 0.6N (Minimum value is Typical)

Speed of Peeling off: 300mm/min.

14.5 Dimensions of Leader-tape, Trailer and Reel

(in:mm)

165 to 180 degree

F

Cover tape

Plastic tape

Empty tape

190min.

Leader

Trailer

Toptape

2.00.5

13.00.2

21.00.8

180

60

9

131.4

1

0

0

3

Directionoffeed

210min.

160min.

1

0

Label

0

.

7

3

0

.

0

3

2.00.05

2.00.05

4.00.1

1.5+0.1

-0

1

.

7

5

0

.

1

3

.

5

0

.

0

5

8

.

0

0

.

2

引き出し方向

0.55以下

0.600.03

Directionoffeed

(in:mm)

0.770.03

0.

9

7

0.

0

3

0.8max.

* (1)(2)(3)(4)indicates

terminalnumber

(1)

(2)

(3)

(4)

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14.6Markingforreel

Customerpartnumber,MURATApartnumber,Inspectionnumber(1),RoHSmarking(2),Quantity,etc

1)ExpressionofInspectionNo. □ □ OOOO

(1)(2)(3)

(1)FactoryCode

(2)DateFirstdigit:Year/Lastdigitofyear

Seconddigit:Month/. → 1to9,. → O,N,D

Third,Fourthdigit:Day

(3)SerialNo.

2)ExpressionofRoHSMarkingROHS – Y()

(1)(2)

(1)RoHSregulationconformityparts.

(2)MURATAclassificationnumber

14.7MarkingforOutsidepackage

CustomernamePurchasingOrderNumber,CustomerPartNumber,MURATApartmentnumber,

RoHSMarking(2),Quantity,etc

14.8SpecificationofOuterCa

OuterCaDimensions

(mm)

StandardReelQuantityinOuterCa

(Reel)

WDH

186186935

ndsonaquantityofanorder.

15. !弹力产生条件 Caution

15.1MountingDirection

Mountproductsinrightdirection.

Wrongdirectionwhichis90rotatedfromrightdirectioncausnotonlyopenorshortcircuitbutalsoflamesor

otherrioustrouble.

15.2LimitationofApplications

Pleacontactusbeforeusingourproductsfortheapplicationslistedbelowwhichrequireespeciallyhigh

reliabilityforthe preventionofdefectswhichmightdirectlycaudamagetothethirdparty'slife,bodyor

property.

(1)Aircraftequipment(6)Transportationequipment(vehicles,trains,ships,etc.)

(2)Aerospaceequipment(7)Trafficssignalequipment

(3)Underaequipment(8)Disasterprevention/crimepreventionequipment

(4)Powerplantcontrolequipment(9)Data-processingequipment

(5)Medicalequipment(10)Applicationsofsimilarcomplexityand/orreliability

requirementstotheapplicationslistedintheabove.

Thisproductisdesignedforsoldermounting.(reflowsolderingonly)

Pleaconsultusinadvanceforapplyingothermountingmethodssuchasconductiveadhesive.

16.1FluxandSolder

FluxUrosin-badflux,butn春节假期法定几天 othighlyacidicflux(withchlorinecontentexceeding0.2(wt)%.)

Donotuwater-solubleflux.

SolderUSn-3.0Ag-0.5Cusolder

UofSn-Znbadsolderwilldeteriorateperformanceofproducts.

IncaofusingSn-Znbadsolder,pleacontactMuratainadvance.

16.2Asmbling

Preiphone怎么重启

-heatingshouldbeinsuchawaythatthetemperaturedifferencebetweensolderandceramicsurfaceis

limitedto100olingintosolventaftersolderingshouldbeinsuchawaythatthetemperature

differenceislimitedto100Cmax.表示声音的词语有

Z Z

rightdirection

wrongdirection

W

D

Label

H

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16.3Resincoating

Theimpedancevaluemaychangeand/oritmayaffectontheproduct'sperformanceduetohighcure-stressof

resintobeudforcoating/

priortou,pleamakethereliabilityevaluationwiththeproductmountedinyourapplication.

g

ThefollowingshallbeconsideredwhendesigningandlayingoutP.C.B.'s.

(1)edesignedsothatproductsarenotsubjecttothemechanicalstressduetowarpingthe

board.

[Productsdirection]

Productsshallbelocationthesideways

Direction(Length:awrappingdirection2.

(2)tion

Itiffectivetoimplementthefollowingmeasures,toreducestressinparatingtheboard.

Itisbesttoimplementallofthefollowingthreemeasures;however,implementasmanymeasures

aspossibletoreducestress.

ContentsofMeasuresStressLevel

(1)Turnthemountingdirectionofthecomponentparalleltotheboardparationsurface. $A>D*1$

(2) Add slits in the board separation part. $A > B$

(3) Keep the mounting position of the component away from the board separation surface. $A > C$

*1 $A > D$ is invalid when stress is added vertically to the perforation as with Hand Separation.

If a Cutting Disc is used, stress will be diagonal to the PCB, therefore $A > D$ is invalid.

(3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection

the component in a position as far away

from the screw holes as possible.

Poor example

Good example

b

a

b

a

b

a

Wrappingdirection1

Wrappingdirection2

ScrewHole

Recommended

D

Perforation

Slit

A

B

C

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Pick-upnozzle

Supportpin

P.C.B.

Product

edesignedsothatproductsare

farfromtheportionofperforation.

Theportionofperforationshallbedesigned

asnarrowaspossible,andshallbedesigned

soasnottobeappliedthestressinthe

tion.

Productsshallnotbearrangedontheline

ofariesofholeswhentherearebig

holesinP.C.B.

(Becausthestressconcentrateonthe

lineofholes.)

SupportpinsshallbetunderP.C.B.

topreventcausingawarptoP.C.B.

duringplacingtheproductsontheother

sideofP.C.B.

otbeparatedwithhand.

g.

ng

Incaofmountingbyuofmountingmachine,pleachoonozzlewhichcanpickup

componentsof0603size.

16.7StandardLandDimensions

○

○

P.C.B.

Portionof

Perforation

Portionof

Perforation

Product

Product

P.C.B.

Hole

o

0

.

8

0

0.30

0

.

3

0

0.90

*(1)(2)(3)(4)In收获作文600字 dicateterminalnumber

Resist

Copperfoilpattern

Nopattern

(in:mm)

(1)(2)

(4)(3)

0

.

5

0

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16.8Soldering(Reflowsoldering)

Standardsolderingprofileandthelimitsolderaabc式词语 ingprofileisasfollows.

Theexcessivelimitsolderingconditionsmaycauleachingoftheelectrodeand/orresultinginthe
deteriorationofproductquality.

StandardProfileLimitProfile

Pre-heating150 ~ 180C、 90s30s

Heatingabove220C、 30s ~ 60sabove230C、 60smax.

Peakt第五元素插曲 emperature2453C260C、 10s

Cycleofreflow2times2times

(1)Standardprintingpatternofsolderpaste

- Standardthicknessofthesolderpasteshouldbe100to150m.
- Uthesolderpasteprintingpatternoftherightpattern.
- Fortheresistandcopperfoilpattern,ustandardlanddimensions.
- USn-3.0Ag-0.5Cusolder.

(2)ReworkingwithSolderingiron

- The following conditions shall be strictly followed when using a soldering iron after being

mounted by reflow soldering.

Pre-heating: 150°C, 1 min Soldering iron output: 30W max.

Tip temperature: 380°C max. Tip diameter: 3mm max.

Soldering time: 3(+1, -0) s. Times: 2 times max.

- Do not touch the products directly with the tip of the soldering iron.

(3) Solder Volume

Solder shall be used not to exceed the upper limits as shown below.

Accordingly increasing the solder volume, the mechanical stress on the product is also increased.

Excessive solder volume may cause the failure of mechanical or electrical performance.

16.9 Cleaning Conditions

Products shall be cleaned on the following conditions.

(1) Cleaning temperature shall be limited to 60°C max. (40% propyl alcohol.)

(2) Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon

on the mounted products and P.C.B..

Power:20W/lmax. Frequency:28kHzto40kHz Time:5minmax.

(3)Cleaner

ativecleaner • Isopropylalcohol(IPA)

sagent • PINEALPHAST-100S

(4)Thereshallbenoresidualfluxandresidualcleaneraftercleaning.

Inthecaofusingaqueousagent,productsshallbedriedcompletelyafterrinwithde-ionized

waterinordertoremovethecleaner.

(5)Othercleaning

Pleacontactus.

StandardProfile

LimitProfile

Temp.

Time

90s30s

230

260

245 3

220

30s ~ 60s

60smax.

180

150

(s)

()

$1/3T - t - T$ (T:Chipthickness)

t

UpperLimit

UpperLimit

Recommendable

Recommendable

(inmm)

0.

5

0

(in:mm)

0.

3

0

0.300.300.30

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16.10Handlingofasubstrate

Aftermountingproductsonasubstrate,donotapplyanystresstotheproductcaudbybendingortwistingto

thesubstratwhencroppingthesubstrate,inrtingandremovingaconnectorfromthesubstrateortightening

screwtothesubstrate蒜蓉粉丝蒸带子 .

Excessivemechanicalstressmaycaucrackingintheproduct.

BendingTwisting

16.11OperatingEnvironment

Donotuthisproductunderthefollowingenvironmentalconditions,ondeteriorationoftheperformance,
suchasinsulationresistancemayresultfromtheu.

(1)incorrosivegas(acidicgas,alkalinegas,chlorine,sulfurgas,organicgasandetc.)

(2)intheatmospherewhereliquidsuchasorganicsolvent,maysplashontheproducts.

16.12StorageConditions

(1)Storageperiod

Utheproductswithin12monthsafterdelivered.

Solderabilityshouldbecheckedifthisperiodixceeded.

(2)Storageenvironmentcondition

- Productsshouldbestoredinthewarehouonthefollowingconditions.

Temperature:-10to+40C

Humidity:15to85%relativehumidity

Norapidchangeontemperatureandhumidity

- Productsshouldnotbestoredincorrosivegas,suchassulfureous,acidgas,alkalinegas,topreventthe followingdeterioration.

Poorsolderabilityduetotheoxidizedelectrode.

- Productsshouldbestoredonthepaletteforthe preventionoftheinfluencefromhumidity,dustandsoon.
- Productsshouldbestoredinthewarehou withoutheatshock,vibration,directsunlightandsoon.
- Productsshouldbestoredundertheairtightpackagedcondition.

(3)Delivery

Care shouldbetakenwhentransportingorhandlingproducttoavoidexcessivevibrationormechanicalshock.

17. !Note

(1)Pleamakesurethatyourproducthasbeenevaluatedinviewofyourspecificationswithourproductbeing mountedtoyourproduct.

(2)Youarerequestednottouourproductdeviatingfromthereferencespecifications.

(3)Thecontentsoftapproveour

productspecificationsortransacttheapprovalsheetforproductspecificationsbeforeordering.

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